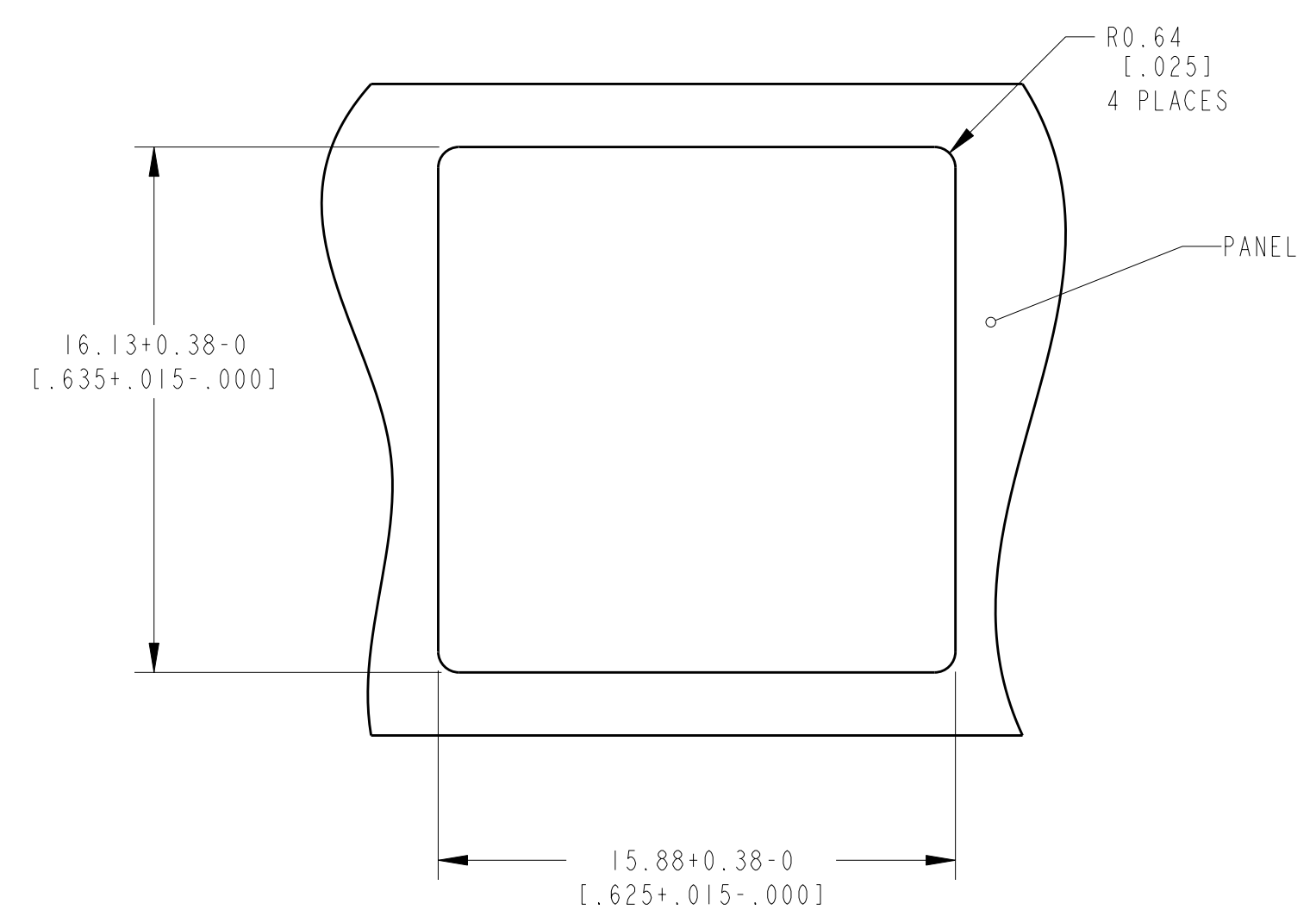
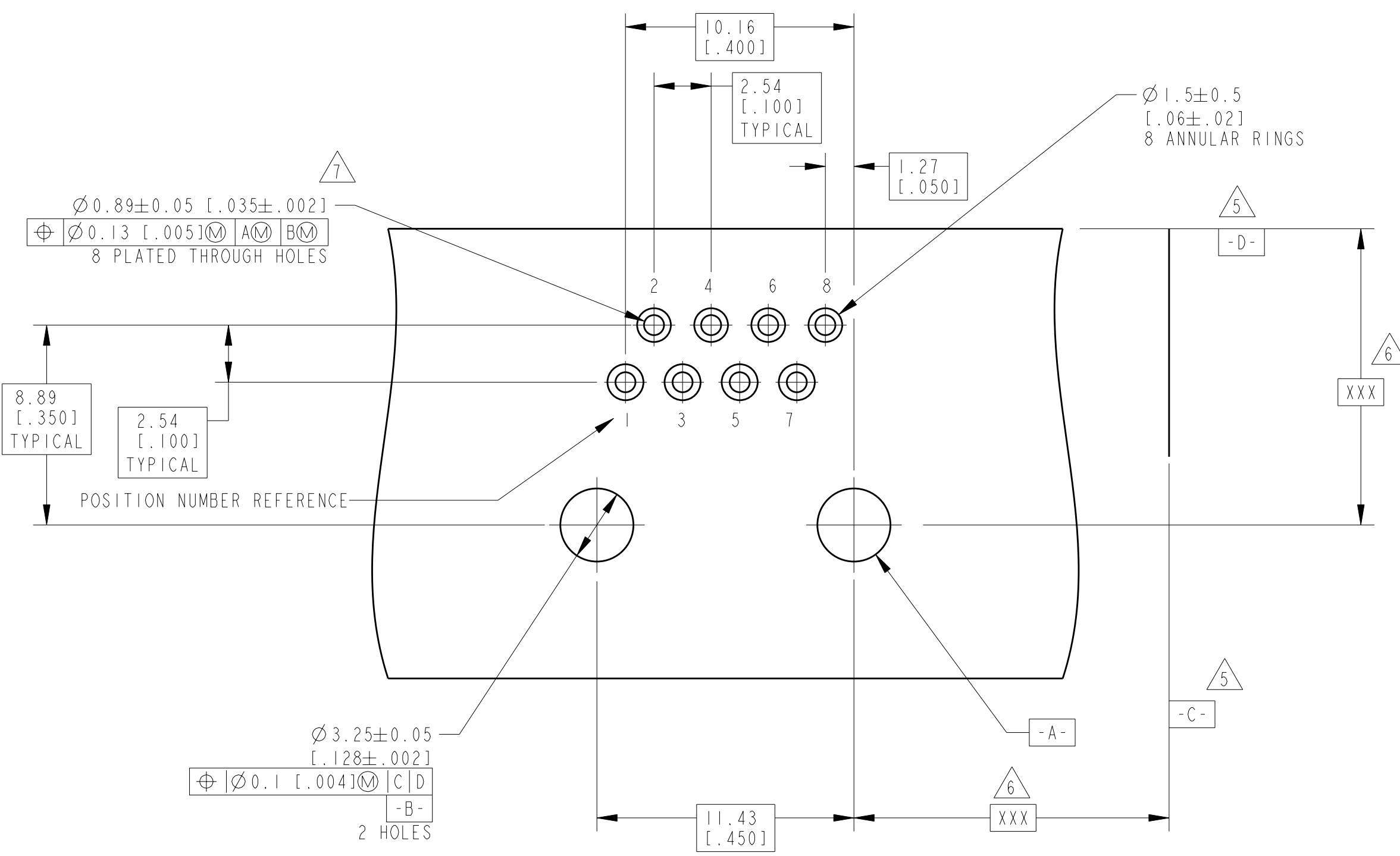
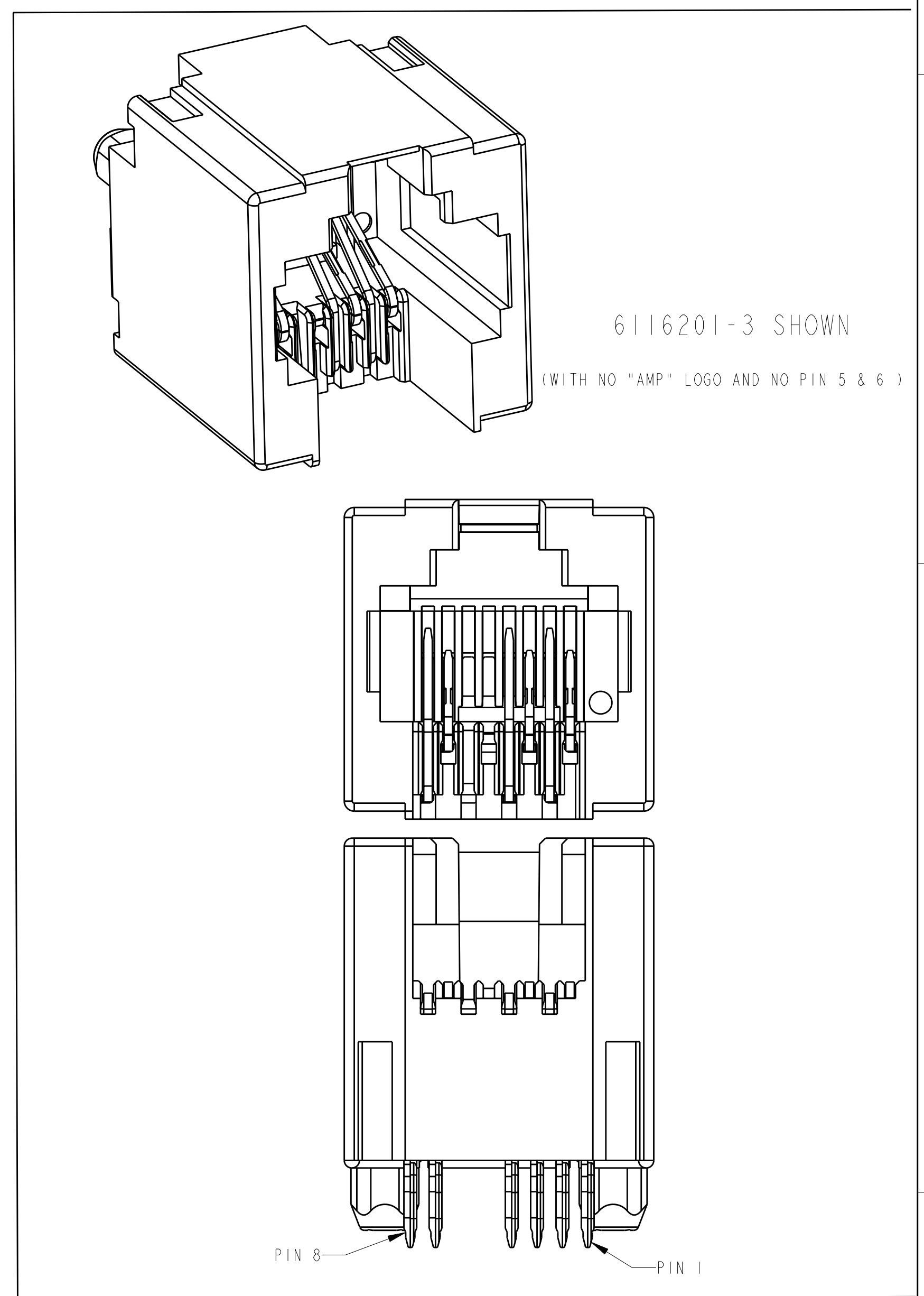
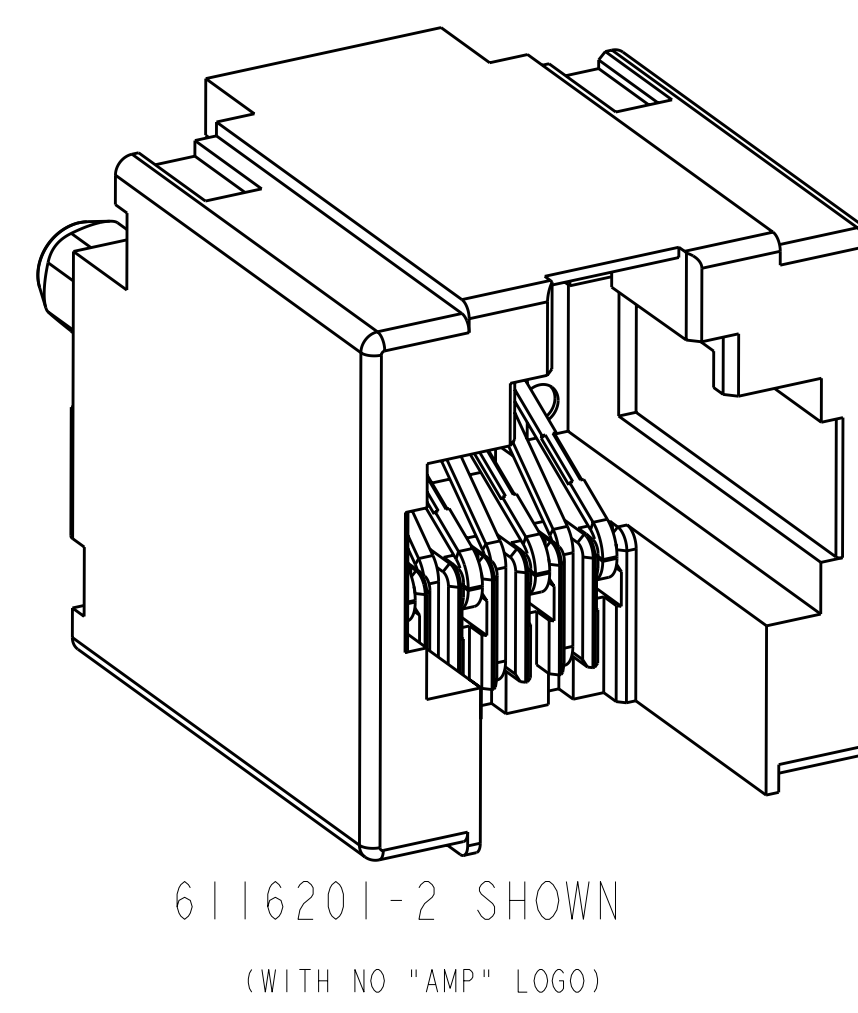
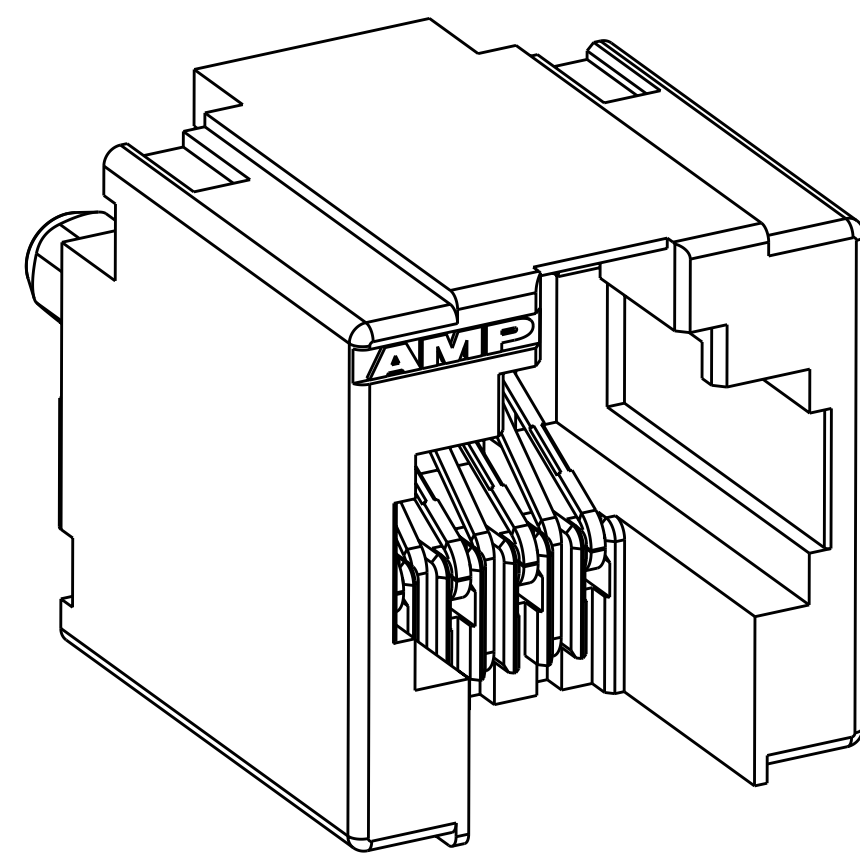
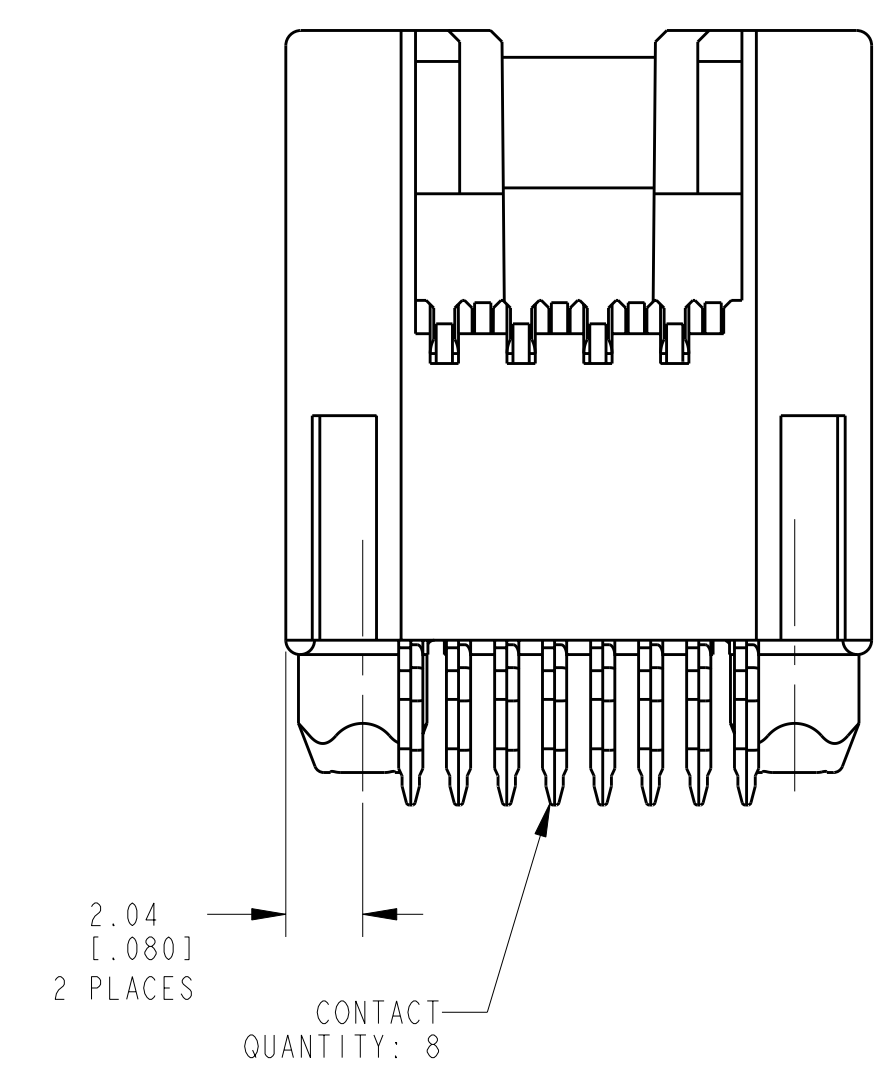
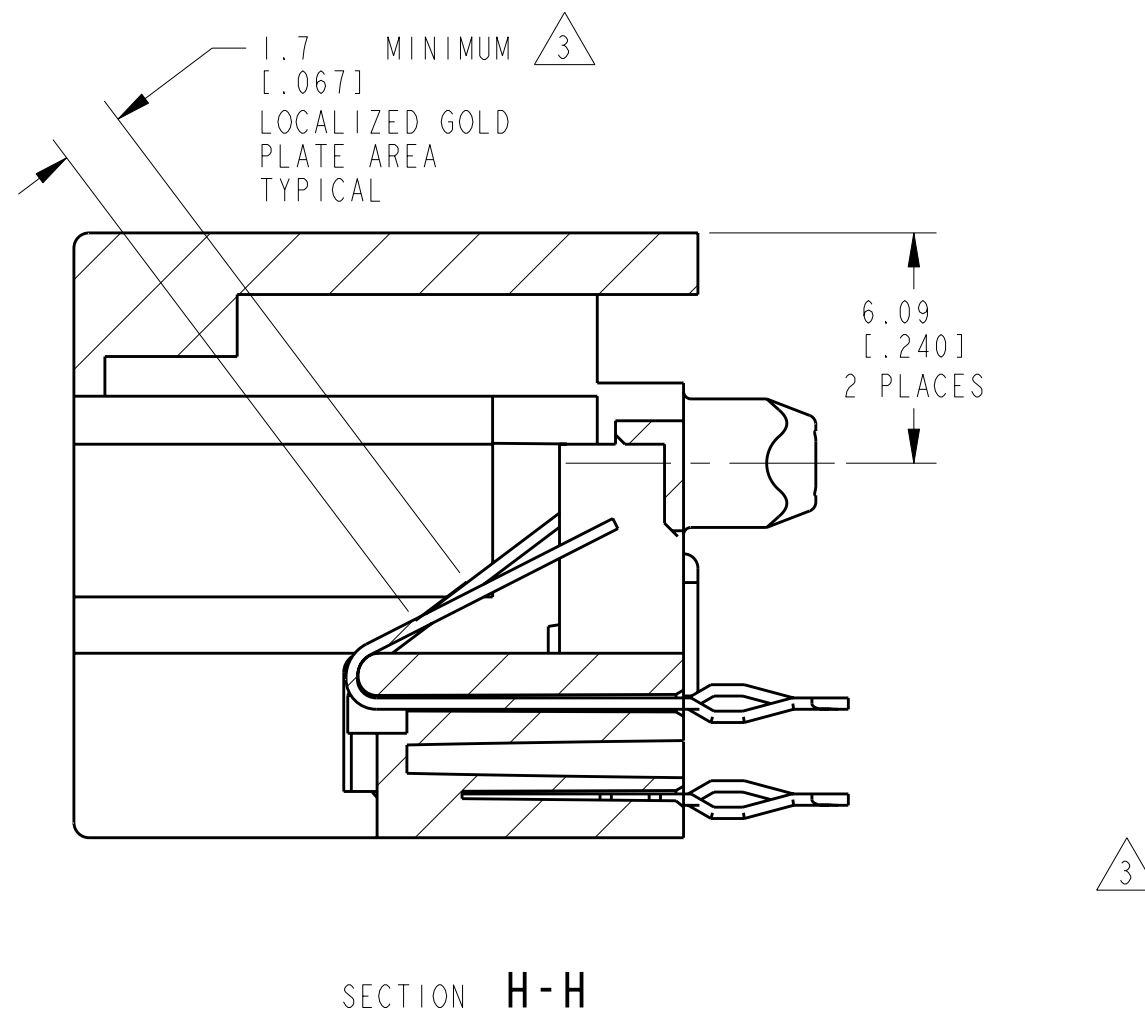
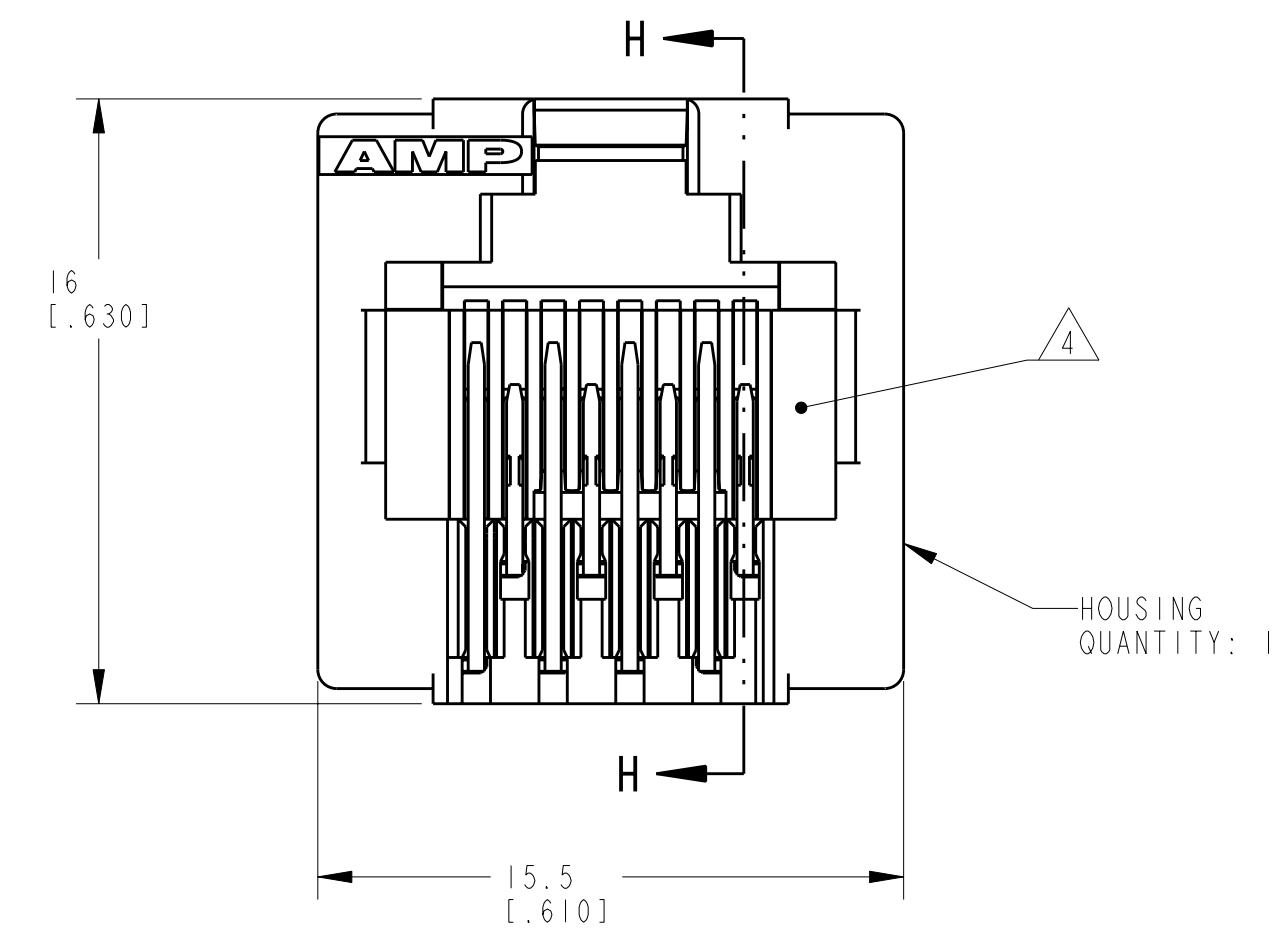


LOC	DIST	REV	DATE	BY	CHK	APPV
AA	22	A	29JUL2005	AF	SF	
		A1	16AUG2010	DZ	MO, W	
		A2	25AUG2010	DZ	MO, W	

- 1 THERMOPLASTIC, COLOR-BLACK.
- 2 PHOSPHOR BRONZE
- 3 1.27um[.000050] MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2um[.000079] MIN MATTE TIN ON TERMINATION END, BOTH OVER 1.27um[.000050] MIN NICKEL.
- 4 CAVITY CONFORMS TO FCC 47 CFR 68 PART F.
- 5 DATUMS ESTABLISHED BY CUSTOMER.
- 6 DIMENSIONS ESTABLISHED BY CUSTOMER.
- 7 DRILLED HOLE DIAMETER 1.02±0.03[.040.001], COPPER THK 0.03-0.08[.001-.003], TIN THICKNESS 8um[.000315] MIN.
- 8 PC BOARDS GREATER THAN 1.57[.062] IN THICKNESS MAY REQUIRE SPECIAL EXTRACTION TOOLING, CONSULT ENGINEERING.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
 RECOMMENDED PRINTED CIRCUIT BOARD THICKNESS 1.41[.055] MIN
 COMPONENT SIDE OF PRINTED CIRCUIT BOARD

DESCRIPTION	PART NUMBER
NO "AMP" LOGO, NO PIN 5 & 6	6116201-3
NO "AMP" LOGO	6116201-2
AS SHOWN	6116201-1

DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED:		MATERIAL	
9 PLC	±	9 PLC	±	HOUSING: 1	CONTACT: 2
1 PLC	±	1 PLC	±0.13[.005]		
2 PLC	±	2 PLC	±		
3 PLC	±	3 PLC	±		
4 PLC	±	4 PLC	±		
5 PLC	±	5 PLC	±		
6 PLC	±	6 PLC	±		
7 PLC	±	7 PLC	±		
8 PLC	±	8 PLC	±		
ANGLES	±	ANGLES	±		
FINISH		FINISH		CUSTOMER DRAWING	

NAME	PRODUCT SPEC	APPLICATION SPEC	SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
TYCO Electronics	108-1163-6	114-2158	A1	00779	6116201	
MODULAR JACK ASSEMBLY, VERTICAL, COMPLIANT PIN, 8 POSITION, CATEGORY 5		SCALE 5:1		SHEET 1 OF 1		REV A2

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)